



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Lloyd G. Burrell et al.

Serial No.: 09/805,027

Group Art Unit: 2822

Filed: March 12, 2001

Examiner: M. Lewis

For: COPPER TO ALUMINUM INTERLAYER INTERCONNECT USING
STUD AND VIA LINER

*entered by RCE
filed 8/28/05
Shaw 8/30/05*

Commissioner for Patents
United States Patent and Trademark Office
P. O. Box 1450
Alexandria, Virginia 22313-1450

SUPPLEMENTAL AMENDMENT UNDER 37 C. F. R. §1.116

Sir:

In response to the Office Action mailed April 20, 2005, and replacing the unentered amendment filed June 20, 2005, please amend the above-identified application as follows (referenced to the amendment filed December 10, 2004):

No amendments to the specification are
presented in this paper.

Amendments to the claims begin on page 2 of
this paper.

Remarks begin on page 5 of this paper.

BOX "AF"
RESPONSE UNDER 37 C.F.R. § 1.116
---EXPEDITE PROCEDURE---
EXAMINING GROUP 2822